

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	245615	probe	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/12 16:01
2	BRS	L2	190397 3	finger or beam or lead or extention	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/12 16:02
3	BRS	L3	271496 4	recess or hole or trench or channel	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/12 16:03
4	BRS	L4	112983	sacrific\$4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/12 16:03
5	BRS	L6	0	(1 same <sup>9</sup> <del>(8)</del> near8 (extend\$4 or cantilever or beyond) near8 (edge or sidewall or end) <sup>near</sup>	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/12 16:05

L1 near8 (form\$4 or deposit\$4 or grow\$4) near8 3

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L5	3	1 same 2 same 3 same 4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/12 16:14
7	BRS	L7	41681	2 near8 (damage or fractur\$4 or break\$4)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/12 16:15
8	BRS	L8	29870	2 near4 (damage or fractur\$4 or break\$4)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/12 16:16
9	BRS	L9	18913	2 same (remov\$4 or etch\$4 or cut\$4 or saw\$4) near4 (substrate or wafer or die or dice)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/12 16:18